

10

9

8

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6

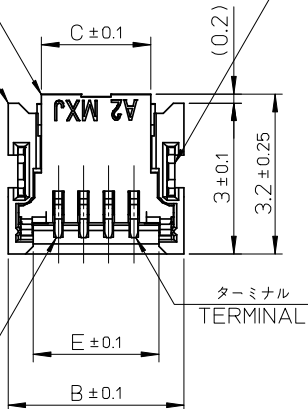
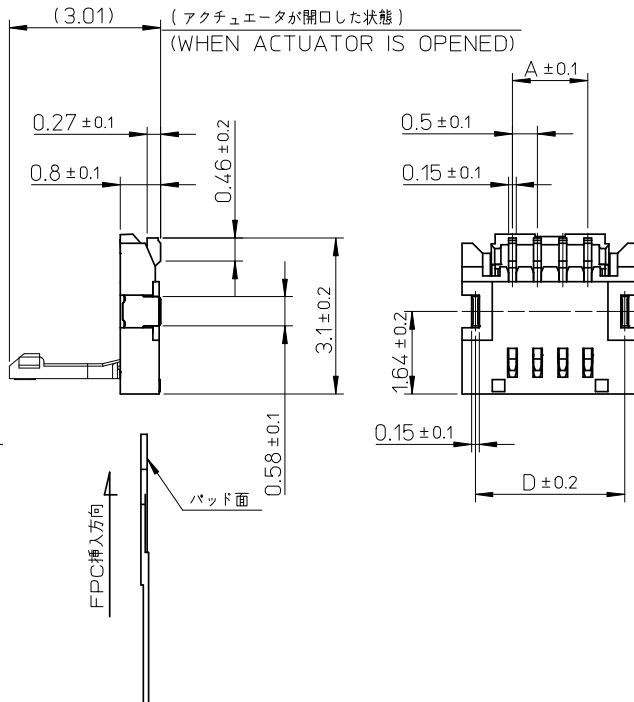
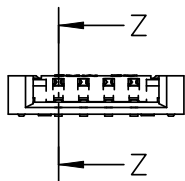
5

4

3

2

1

アクチュエータ
ACTUATORハウジング
HOUSING補強金具
FITTING NAIL回路番号 1
CIRCUIT NO.1注記
NOTES:

1.材質

MATERIAL

ハウジング: 耐熱性樹脂、ガラス充填、UL94V-0

HOUSING: HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0

アクチュエータ: 耐熱性樹脂、ガラス充填、UL94V-0

ACTUATOR: HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0

ターミナル: 銅合金 (t=0.15)

TERMINAL: COPPER ALLOY (t=0.15)

補強金具: 銅合金 (t=0.15)

NAIL: COPPER ALLOY (t=0.15)

2.めっき仕様

PLATING

ターミナル: 部分金メッキ

接点部 0.1マイクロメートル以上

半田付け部 0.05マイクロメートル以上

TERMINAL: SEPARATED GOLD PLATING

CONTACT AREA 0.1 MICROMETER MINIMUM.

SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.

下地 ニッケルメッキ 1.0マイクロメートル以上

UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.

補強金具: 銅メッキ 1.0マイクロメートル以上

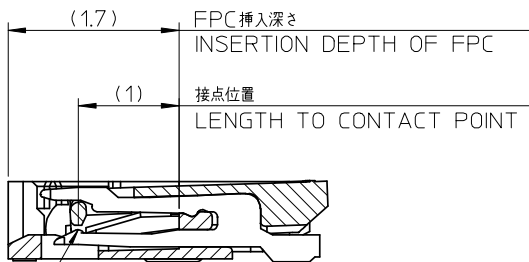
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.

下地 ニッケルメッキ 1.0マイクロメートル以上

UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.

3.平坦度は、0.1mm以下とする。

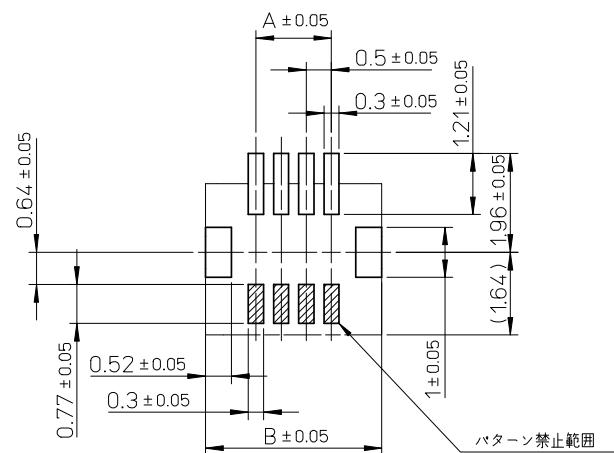
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.

FPC挿入深さ
INSERTION DEPTH OF FPC接点位置
LENGTH TO CONTACT POINT接点部 (下面)
CONTACT POINT
(BOTTOM CONTACT)

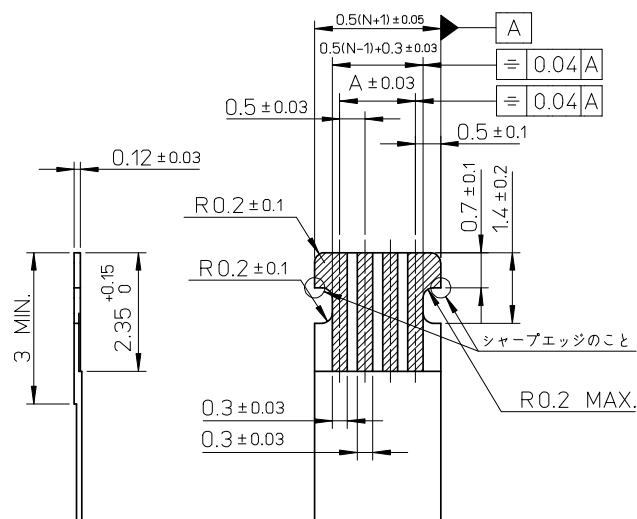
SECTION Z-Z

4.0	4.47	3.68	5.0	3.0	NOT AVAILABLE	NOT AVAILABLE	7
3.5	3.97	3.18	4.5	2.5	501461-0601	501461-0609	6
3.0	3.47	2.68	4.0	2.0	501461-0501	501461-0509	5
2.5	2.97	2.18	3.5	1.5	501461-0401	501461-0409	4
E	D	C	B	A	エンボス極細品 EMBOSSED PACKAGING		製品番号 MATERIAL NO.
					ORDER No. オーダー番号		極数(N) CIRCUITS(N)

REVISED EC NO: J2008-4048 DRAWN:MABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ± 0.2		DRAWN BY DATE RSMIYA 2004/11/10		TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-			
		10 OVER 30 UNDER ± 0.25		CHECKED BY DATE HHIRATA 2004/11/10					
		30 OVER ± 0.3		APPROVED BY DATE MSASAO 2004/11/10		MOLEX MOLEX INCORPORATED			
		ANGULAR ±1 °		MATERIAL NO. SEE TABLE					
		REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



RECOMMENDED P.C. BOARD PATTERN LAYOUT



推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて:

抜き方向は、導体側から補強板側を推奨します。

補強フィルム材質は、ポリイミドを推奨します。

接着剤は、熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

ABOUT FPC :

RECOMMENDED PUNCHER DIRECTION :

FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.

RECOMMENDED_MATERIAL

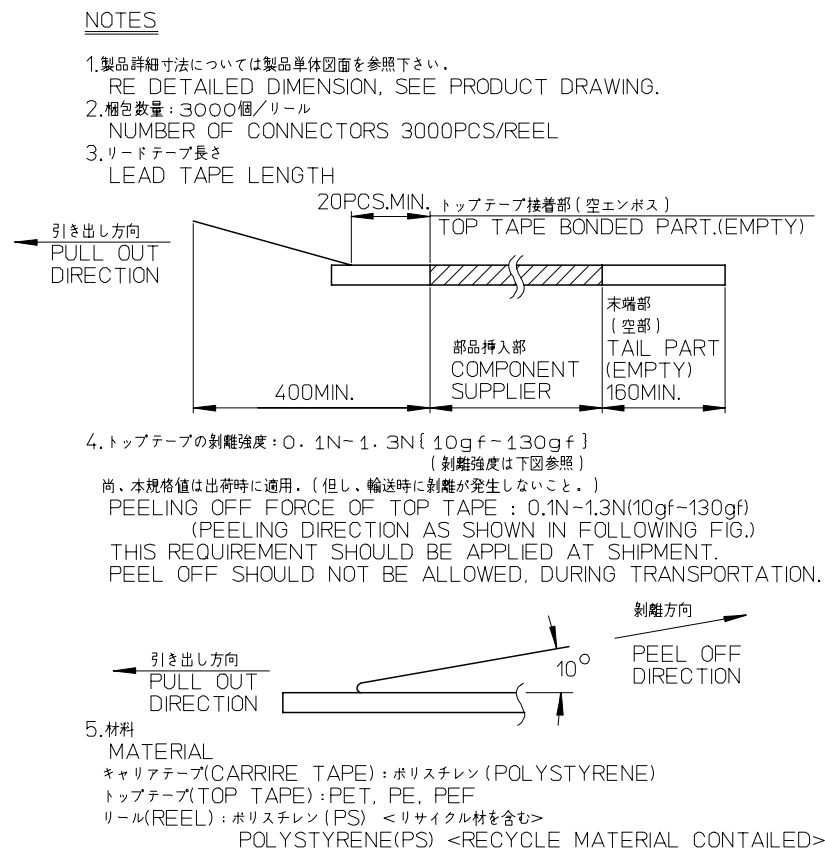
STIFFNER FILME : POLYIMIDE

BONDING AGENT : THERMOSETTING AGENT

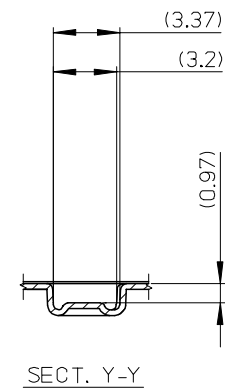
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE MAY CAUSE

THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRAWN:MABEL CHKD:THIRUJAYA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY RSMUYIA	DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2004/11/10				
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2004/11/10				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-501461-001		2 OF 2		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



tb_frame_A3_J_ME_S
Rev. D 2004/04/02



TOLERANCES SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	501461-xx01	MODEL NO.
							 THIRD ANGLE PROJECTION	

tb_frame_A3_J_ME_S
Rev. D 2004/04/02